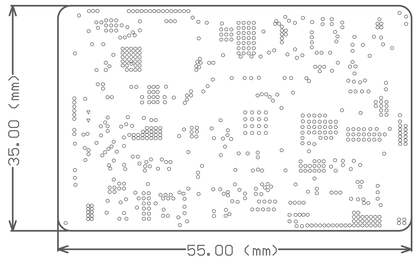
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.020mm	3.5	
1	L1_Top		0.036mm		
	Dielectric 1	PP-006	0.117mm	4.1	
2	L2_GND	CF-004	0.030mm		
	Dielectric1	FR-4	0.152mm	4.3	
3	L3_Digital		0.030mm		
	Dielectric4	FR-4	0.903mm	4.3	
4	L4_Analog		0.030mm		
	Dielectric10	FR-4	0.152mm	4.3	
5	L5_GND	CF-004	0.030mm		
	Dielectric 2	PP-006	0.117mm	4.1	
6	L6_Bot		0.036mm		
	Bottom Solder	Solder Resist	0.020mm	3.5	
	Bottom Overlay				
Total board thickness:			1.673mm		



NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED.
2. MATERIAL :
   A. FR4 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION.
3. DRILLING :
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol.
      UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
   COPPER PLATING IN THRU-HOLES 35um.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE AND LOGO SYMBOL IN ETCH (PREFERRED) OR SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION:
   A. SOLDERMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGEABLE
      MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDE ARE 1:1. SOLDERMASK COLOR **BLUE**
7. FINISH:
   A. SHALL BE ELECTROLESS NIKEL / IMMERSION GOLD(ENIG).
   B. NICKEL THICKNESS: 2 - 5 MICRONS.
   C. GOLD THICKNESS: 0.04-0.07 MICRONS.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY.
   FLAMMABILITY RATING (94-V0).
9. MANUFACTURED BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD
   IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WARP OR TWIST SHALL NOT EXCEED .010 in/in.
11. THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.
12. CARE MUST BE TAKEN TO AVOID OVER ETCHING OF COPPER ON PADS.
13. PLEASE FOLLOW +/-3mils FOR PTH, +/-2mils FOR NPTH

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
∇	2	25.59mil (0.650mm)	PTH	Round	L1_Top - L6_Bot	Pad	Rounded	(Mixed)
O	664	7.87mil (0.200mm)	PTH	Round	L1_Top - L6_Bot	Via	Rounded	v50h20m0mx0
	666 Total							

Infineon Semiconductor Technologies
Bangalore India

ENGINEER: Shubhendu Sitoke	TITLE: REF_MTR_48V30A_PSC3_GaN MCU board		
PCB DESIGNER: Shubhendu Sitoke			
DATE: 16-07-2026	PART NO.:	REL:	REV: v04
SVN REVISION: Not in version control	FILE NAME: REF_MTR_48VxxA_PSOC_C3_GaN MCU board.PcbDoc	APRV: Marco	SCALE: 1:1

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